

## PATENT

Atty. Dkt. No.: APPM/008241/PPC/ECP/CKIM

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:  
Sun et al.

**Serial No.: 10/616,097**

**Confirmation No.: 1645**

**Filed: July 8, 2003**

# For: Multiple-Step Electrodeposition Process for Direct Copper Plating on Barrier Metals

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**Group Art Unit: 1753**

**Examiner: Edna Wong**

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**Commissioner for Patents**  
**P.O. Box 1450**  
**Alexandria, VA 22313-1450**

**CERTIFICATE OF FACSIMILE  
TRANSMISSION UNDER 37 CFR 1.8**

I hereby certify that this correspondence and the documents referred to as attached therein are being facsimile transmitted to the U.S. Patent and Trademark Office to the fax number indicated by the Examiner, namely, fax number 571.273.8300 to the attention of the named Examiner, on the date below.

December 30, 2005  
Date

Kim R. Rhee  
Signature

**Dear Sir:**

**SECOND RESPONSE TO FINAL OFFICE ACTION DATED OCTOBER 4, 2005**

In response to the Final Office Action dated October 4, 2005, having a shortened statutory period for response set to expire on January 4, 2006, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although the Applicant believes that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/008241/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

**Amendments to the Claims** begin on page 2 of this paper. **Remarks** begin on page 5 of this paper.